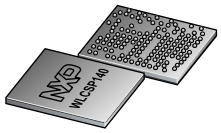


SOT2126-1

WLCSP140, wafer level chip-size package; 140 terminals; 0.3 mm pitch; 4.385 mm x 4.96 mm x 0.455 mm body

5 May 2022 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP140
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-01-2022
Manufacturer package code	98ASA01734D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4.96	-	mm
package width	-	4.385	-	mm
seated height	-	0.455	0.485	mm
nominal pitch	-	0.3	-	mm
actual quantity of termination	-	140	-	

WLCSP140, wafer level chip-size package; 140 terminals; 0.3 mm pitch; 4.385 mm x 4.96 mm x 0.455 mm body

2 Package outline

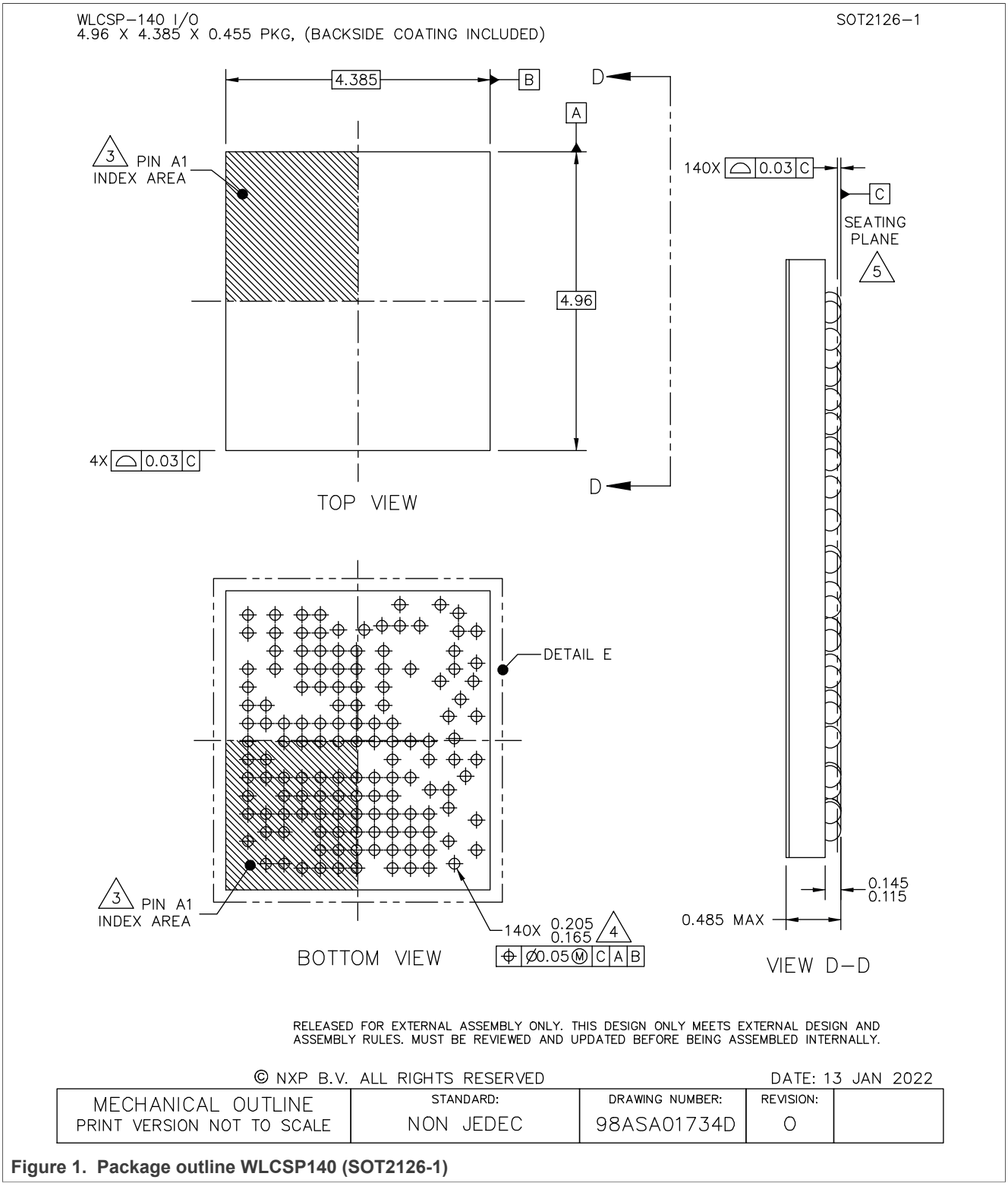


Figure 1. Package outline WLCSP140 (SOT2126-1)

WLCSP140, wafer level chip-size package; 140 terminals; 0.3 mm pitch; 4.385 mm x 4.96 mm x 0.455 mm body

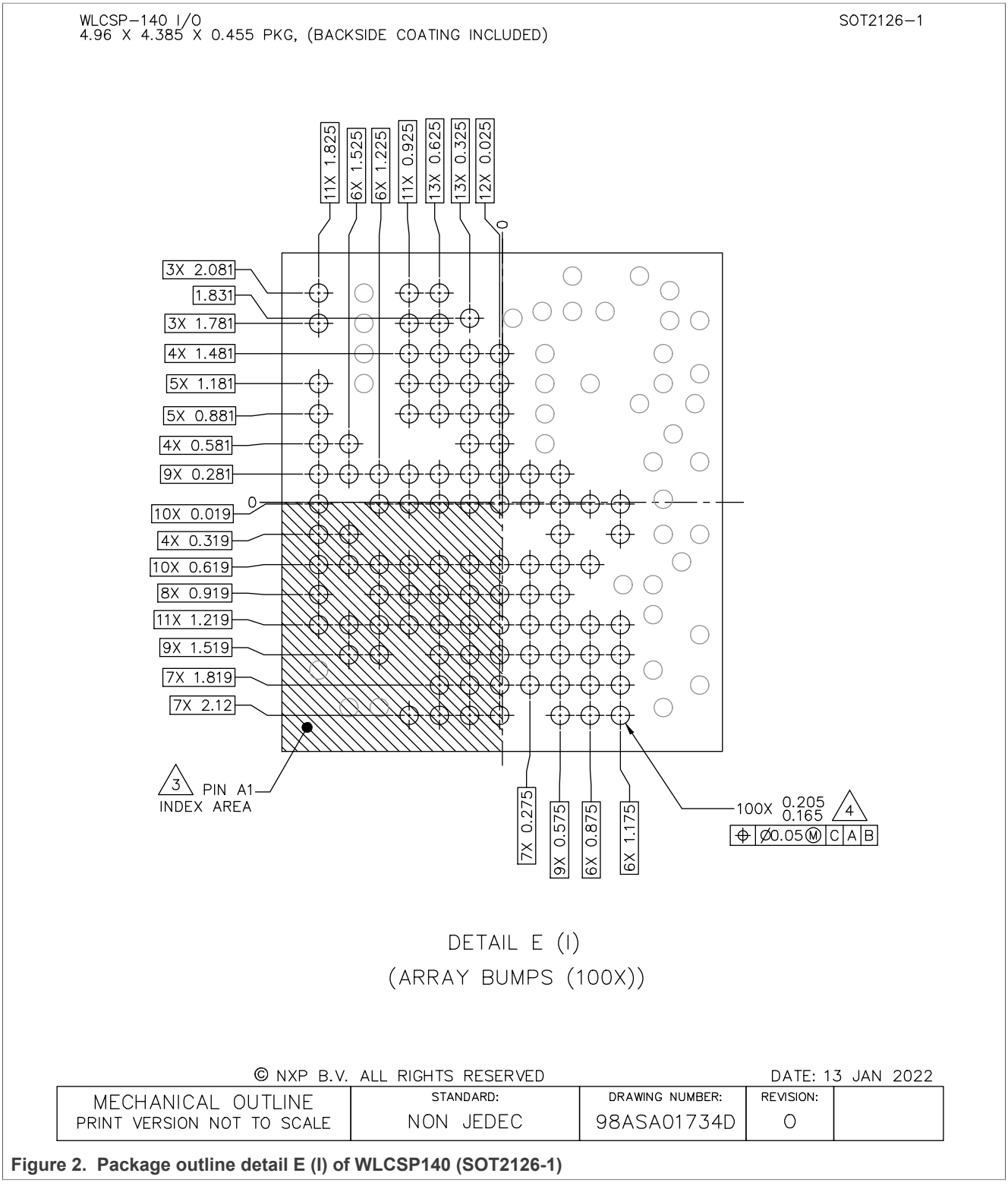


Figure 2. Package outline detail E (I) of WLCSP140 (SOT2126-1)

WLCSP140, wafer level chip-size package; 140 terminals; 0.3 mm pitch; 4.385 mm x 4.96 mm x 0.455 mm body

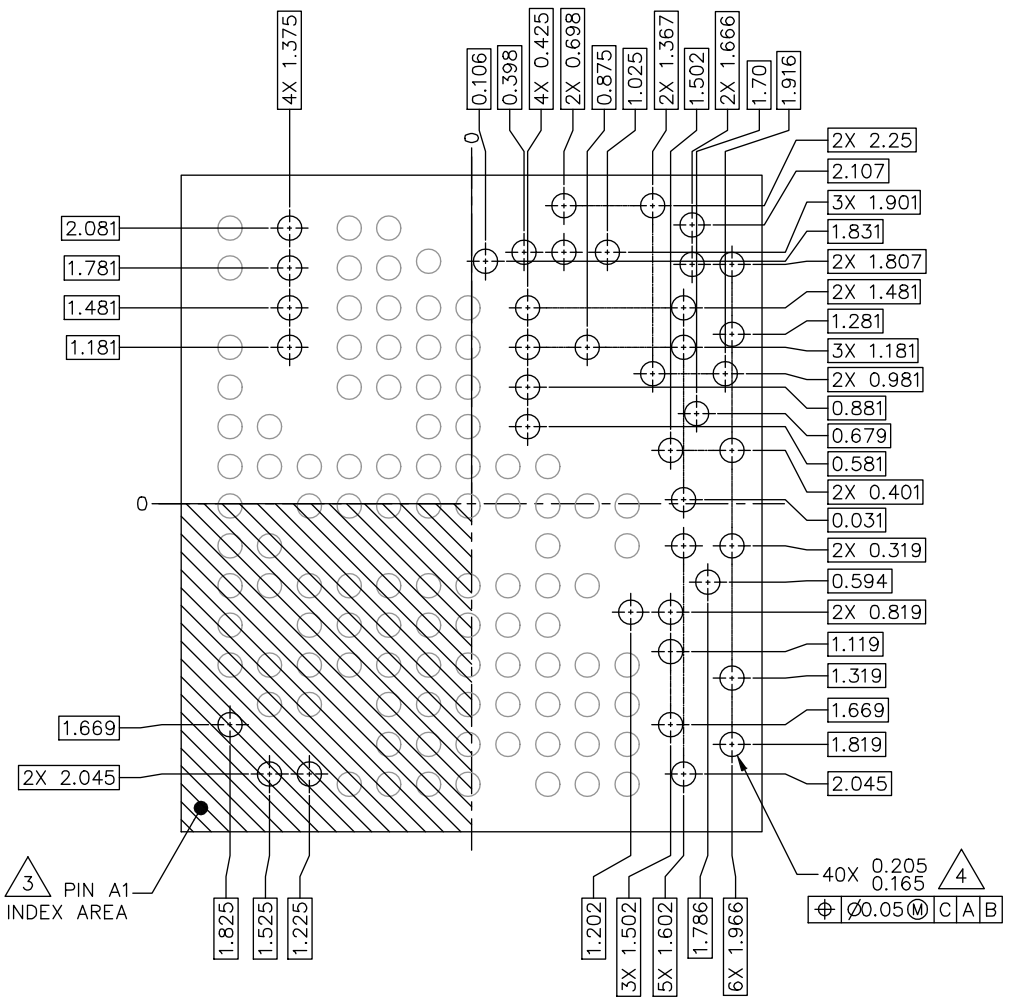


Figure 3. Package outline detail E (II) of WLCSP140 (SOT2126-1)

3 Soldering

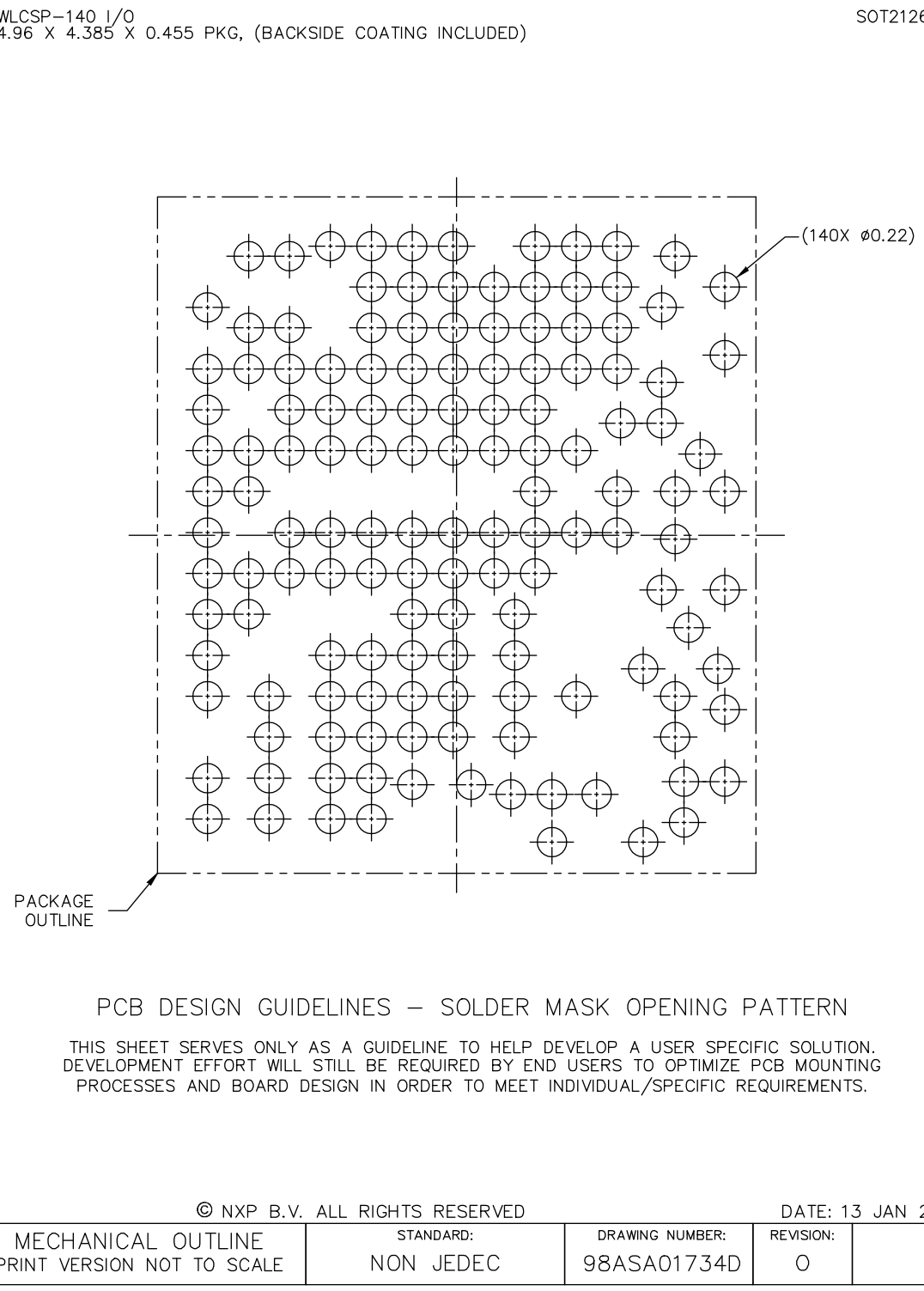


Figure 4. Reflow soldering footprint part1 for WLCSP140 (SOT2126-1)

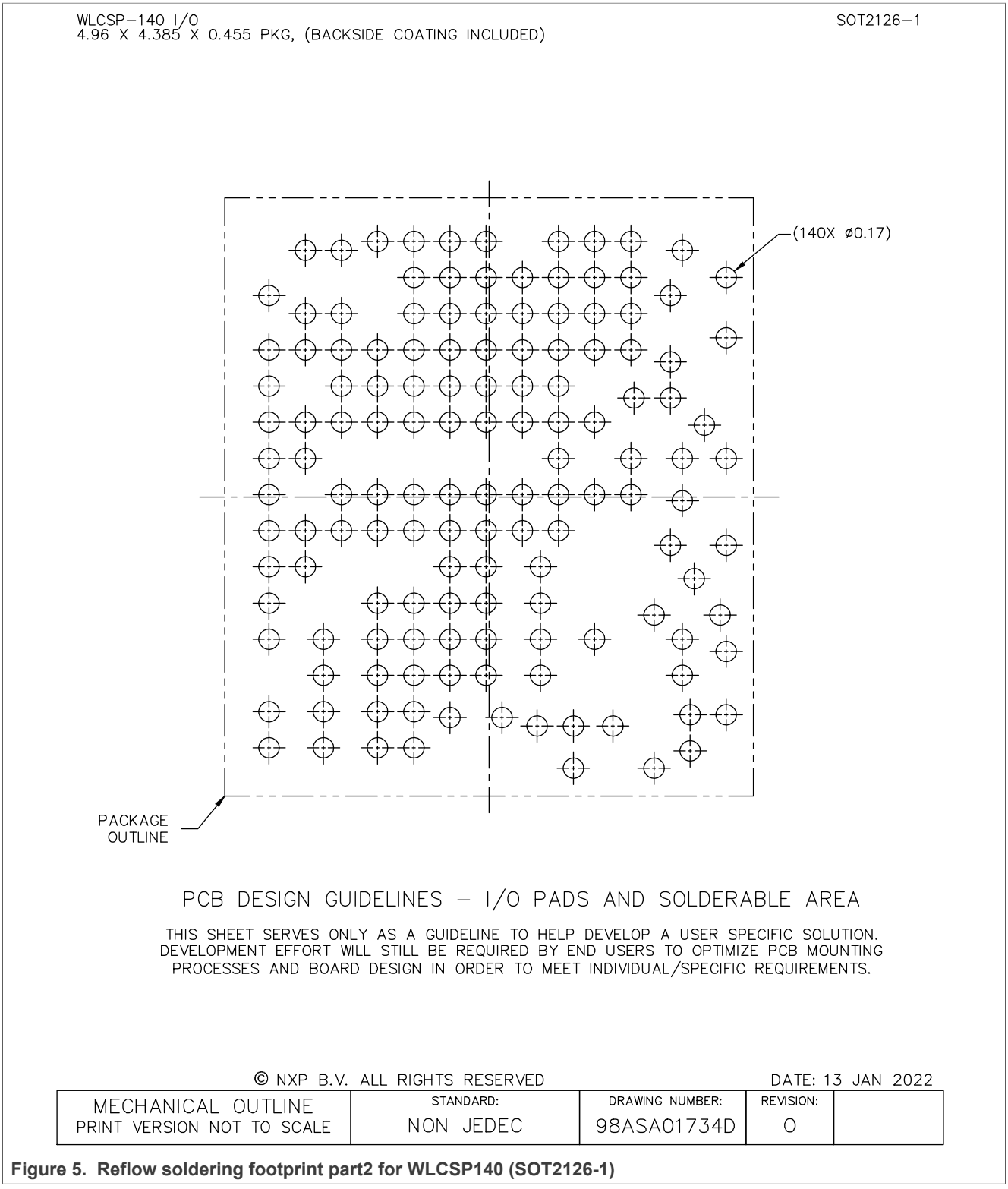


Figure 5. Reflow soldering footprint part2 for WLCSP140 (SOT2126-1)

WLCSP140, wafer level chip-size package; 140 terminals; 0.3 mm pitch; 4.385 mm x 4.96 mm x 0.455 mm body

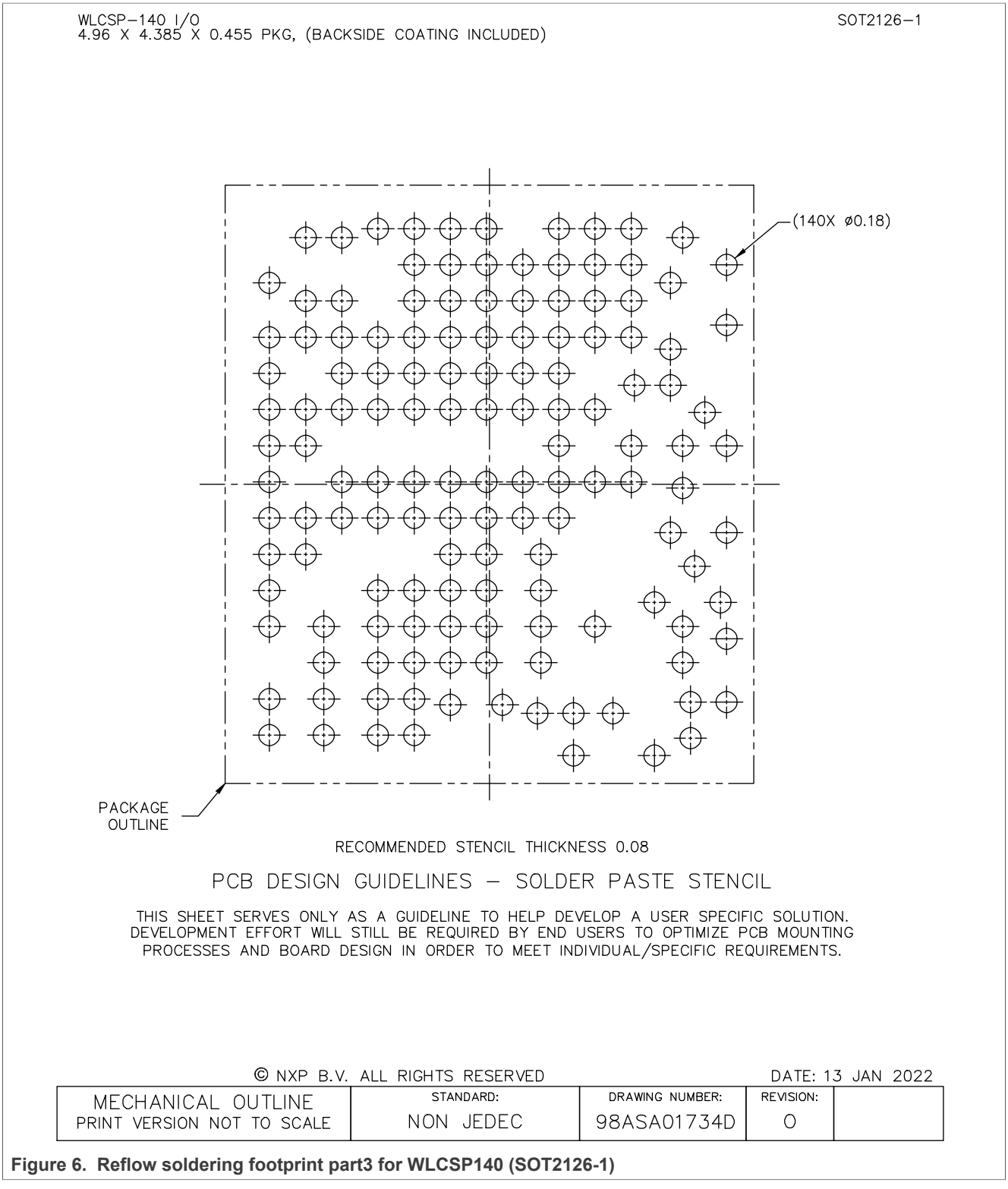
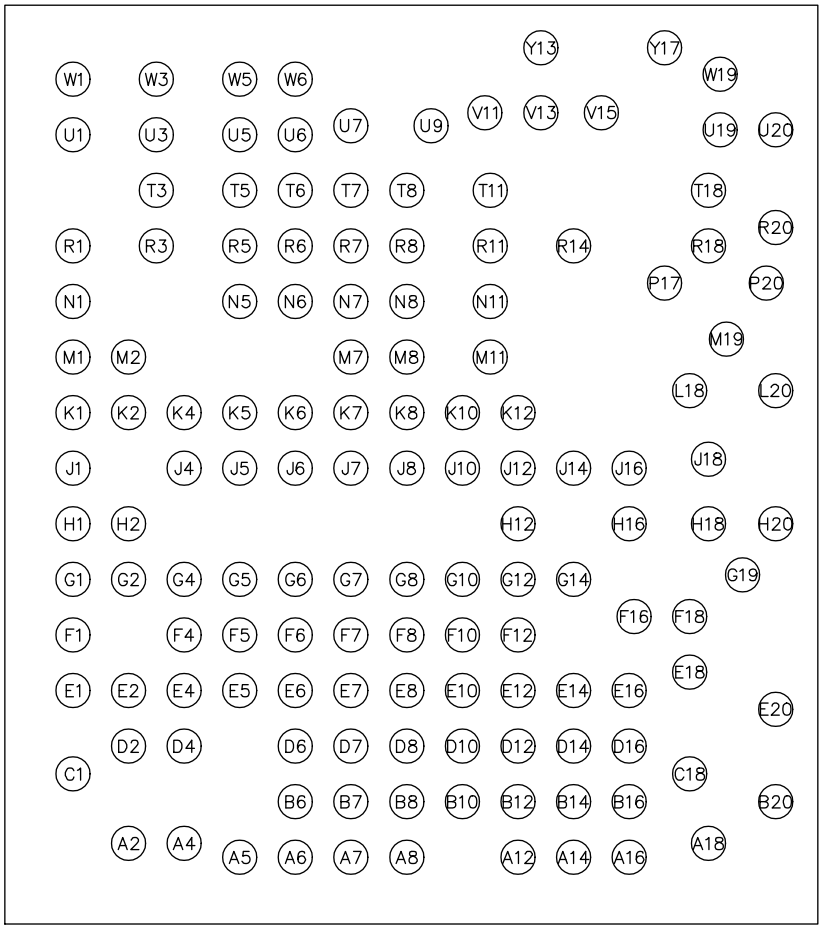


Figure 6. Reflow soldering footprint part3 for WLCSP140 (SOT2126-1)

WLCSP140, wafer level chip-size package; 140 terminals; 0.3 mm pitch; 4.385 mm x 4.96 mm x 0.455 mm body

WLCSP−140 I/O
4.96 X 4.385 X 0.455 PKG, (BACKSIDE COATING INCLUDED)

SOT2126−1



PIN NUMBERS
(VIEWED FROM BOTTOM, SAME AS DETAIL E)

DATE: 13 JAN 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01734D	REVISION: O	

Figure 7. Reflow soldering footprint part4 for WLCSP140 (SOT2126-1)

WLCSP140, wafer level chip-size package; 140 terminals; 0.3 mm pitch; 4.385 mm x 4.96 mm x 0.455 mm body

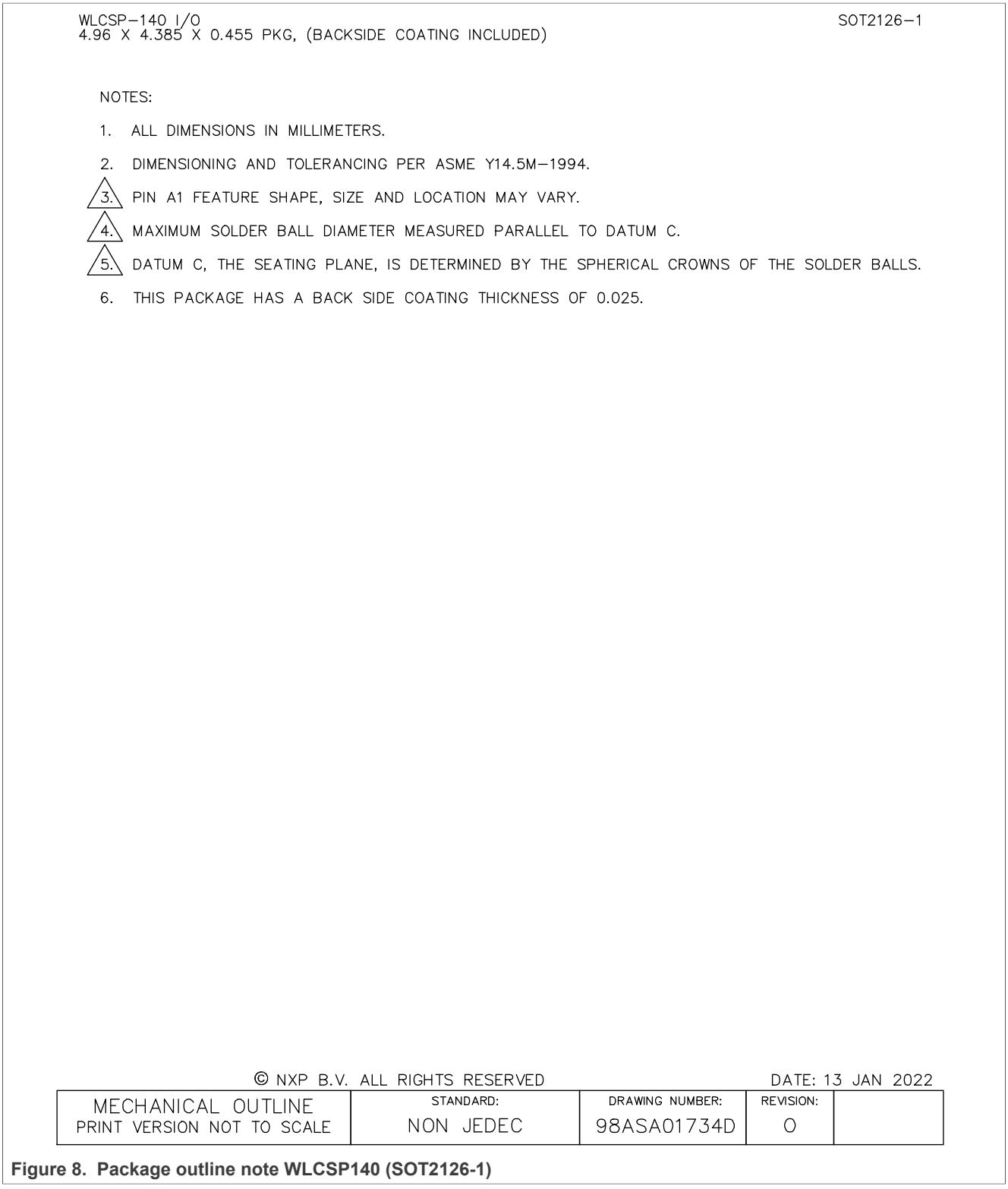


Figure 8. Package outline note WLCSP140 (SOT2126-1)

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WLCSP140, wafer level chip-size package; 140 terminals; 0.3 mm pitch; 4.385 mm x 4.96 mm x 0.455 mm body

Contents

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For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 5 May 2022